Case Study

OEM – Transportation Industry

Technical situation

Customer was using an offshore source to encapsulate their printed circuit board assemblies. At the time the customer contacted PRS they were experiencing field failures, units were non functional, truck lines and factory lines were down.

Solution

PRS worked closely with the OEM, gathering detailed data necessary to develop the appropriate process for this application. After further evaluation the PRS engineering team presented a potting/encapsulation solution. The encapsulation compound chosen provided high electrical insulation, thermal conductivity, excellent heat transfer and high voltage insulation. Ionic cleanliness testing was added to the process.

Benefits

Within 5 business days PRS submitted first articles. Assemblies were subjected to a series of environmental stress screening tests to validate the PRS process. Assemblies passed with a 100% first time yield. The process was approved and implemented immediately; lines were back up and running. OEM moved production of their product back to the US.